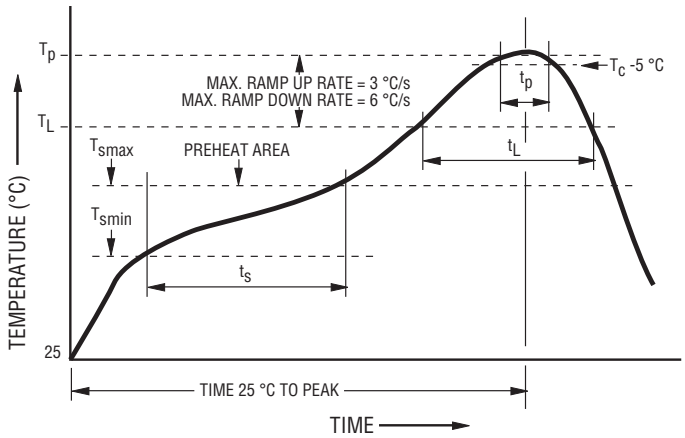
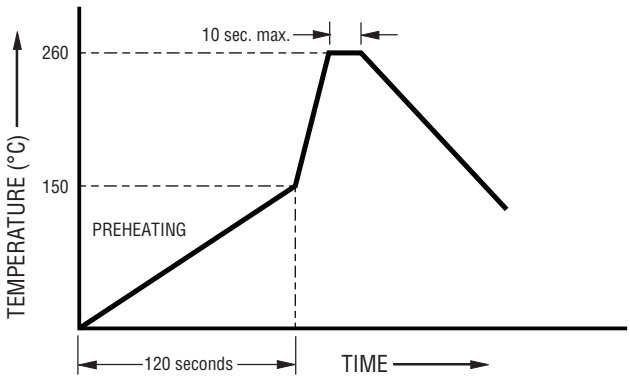
Solder Reflow Recommendations



Profile Feature	Pb-Free Assembly
Preheat / Soak: Temperature Min. (T_{smin}) Temperature Max. (T_{smax}) Time (t_s) from (T_{smin} to T_{smax})	 150 °C 200 °C 60~120 seconds
Ramp Up Rate (T_L to T_p)	3 °C / second max.
Liquidous Temperature (T_L) Time (t_L) maintained above T_L	217 °C 60~150 seconds
Peak Package Body Temperature (T_p)	260 °C
Time (t_p)* within 5 °C of the specified classification temperature (T_c)	30 seconds*
Ramp Down Rate (T_p to T_L)	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.

* Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

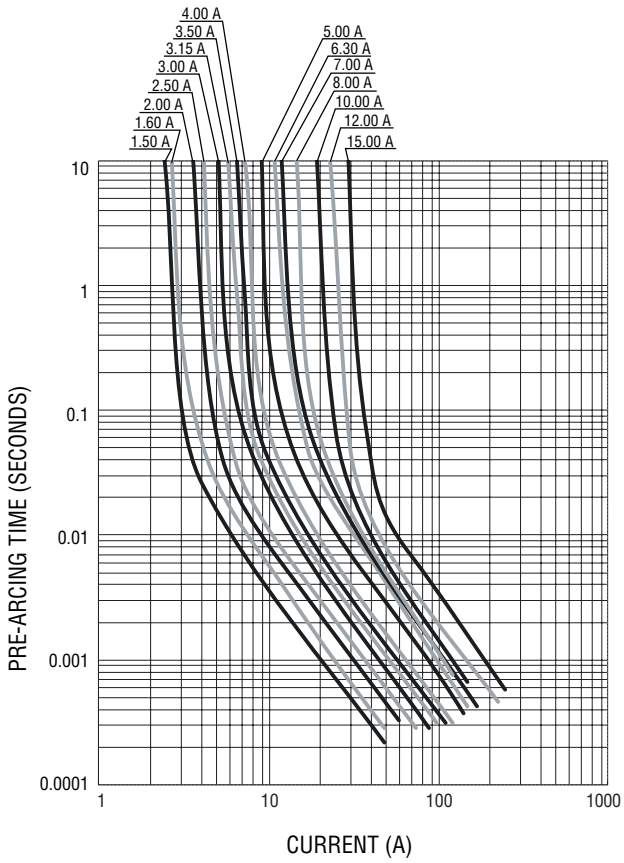
Recommended Temperature Profile for Wave Soldering



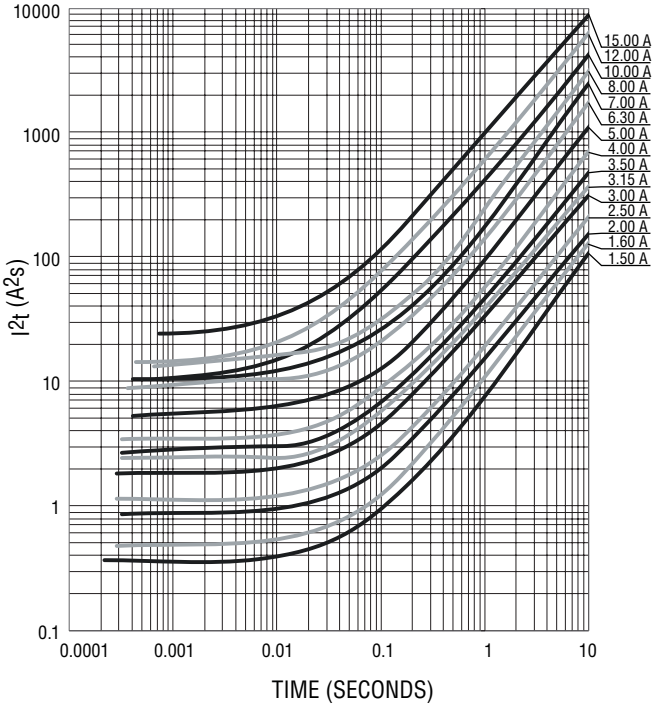
Wave soldering is suitable for 1206 size models.

Specifications are subject to change without notice.
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.
Users should verify actual device performance in their specific applications.

Average Pre-Arcing Time vs. Current Curves



Average I^2t vs. t Curves



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Asia-Pacific: Tel: +886-2 2562-4117 • Email: asiacus@bourns.com
EMEA: Tel: +36 88 520 390 • Email: eurocus@bourns.com
The Americas: Tel: +1-951 781-5500 • Email: americus@bourns.com
www.bourns.com

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